




Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST33KTPM2X32DKG9	U4MG*T4ADKG9	A	993N	26-01-2024
	Amount	UoM	Unit type	ST ECOPACK Grade
	46.88	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Matte Tin	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
EQFN	5x5x0.55mm	32		
Comment	Package : A0B8 UFQFPN 5X5X0.55 32L 0.5 MM PITCH 8202208			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-14th June 2023				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	U4MG*T4ADKG9				5999999.0	1007127.8
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.609	mg	supplier	die	Silicon (Si)	7440-21-3		0.456	mg	748768	9728
				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	29557	384
				supplier	metallization	Copper (Cu)	7440-50-8		0.057	mg	93596	1216
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.009	mg	14778	192
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	3284	43
				supplier	Passivation	Silicon Oxide	7631-86-9		0.067	mg	110016	1429
Leadframe-C7025-Ag	Copper & its alloys	20.100	mg	supplier	Alloy	Cu	7440-50-8		19.246	mg	957500	410576
					Alloy	Ni	7440-02-0		0.599	mg	29800	12778
					Alloy	Si	7440-21-3		0.131	mg	6500	2787
					Alloy	Mg	7439-95-4		0.030	mg	1500	643
					coating	Ag	7440-22-4		0.094	mg	4700	2015
Glue - 8600	M-011 Other inorganic materials	0.763	mg	supplier	Glue	Silver	7440-22-4		0.622	mg	815000	13272
					Glue	(Octahydro-4,7-methano-1H-indenediy)bis(m	42594-17-2		0.046	mg	60000	977
					Glue	exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl met	7534-94-3		0.046	mg	60000	977
					Glue	isobornyl acrylate	5888-33-5		0.046	mg	60000	977
					Glue	2-(3,4-Epoxy cyclohexyl)ethyltrimethoxysilane	3388-04-3		0.004	mg	5000	81
Bonding wire- AuPdCu wire	M-011 Other inorganic materials	0.740	mg	supplier	Bonding wire	Copper	7440-50-8		0.714	mg	965000	15432
					Bonding wire	Palladium	7440-05-3		0.018	mg	24990	400
					Bonding wire	Gold	7440-57-5		0.007	mg	10000	160
					Bonding wire	Silver	7440-22-4		0.000	mg	10	0
Encapsulation - EME-G700LTD	M-011 Other inorganic materials	22.872	mg	supplier	Molding compound	Epoxy Resin	Proprietary		1.144	mg	50000	24719
					Molding compound	Phenol Resin	Proprietary		0.618	mg	27000	13348
					Molding compound	Silica (Amorphous)A	60676-86-0		19.899	mg	870000	430106
					Molding compound	Silica (Amorphous)B	7631-86-9		1.144	mg	50000	24719
					Molding compound	Carbon Black	1333-86-4		0.069	mg	3000	1483
External plating - Matte Tin	M-011 Other inorganic materials	1.790	mg	supplier	Matte tin	Tin	7440-31-5		1.790	mg	1000000	38685